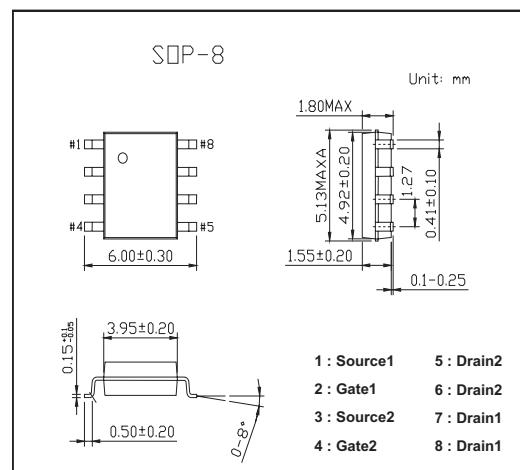
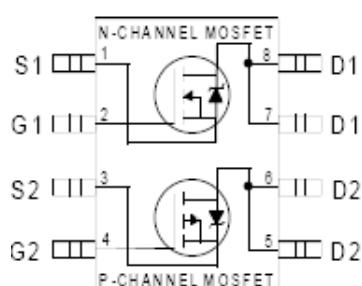


HEXFET® Power MOSFET

KRF9952

■ Features

- Generation V Technology
- Ultra Low On-Resistance
- Dual N and P Channel MOSFET
- Surface Mount
- Very Low Gate Charge and Switching Losses
- Fully Avalanche Rated



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V _{DS}		30	V
Gate-to-Source Voltage	V _{GS}		±20	V
Continuous Drain Current, V _{GS} @ 10V @ T _a = 25°C	I _D	3.5	-2.3	
Continuous Drain Current, V _{GS} @ 10V @ T _a = 70°C	I _D	2.8	-1.8	A
Pulsed Drain Current *1	I _{DM}	16	-10	
Continuous Source Current (Diode Conduction)	I _S	1.7	-1.3	A
Power Dissipation @T _a = 25°C	P _D		2	
Power Dissipation @T _a = 70°C			1.3	W
Single Pulse Avalanche Energy	E _{AS}	44	57	mJ
Avalanche Current	I _{AR}	2.0	-1.3	A
Repetitive Avalanche Energy	E _{AR}		0.25	mJ
Peak Diode Recovery dv/dt *2	dv/dt	5.0	-5	V/ns
Junction and Storage Temperature Range	T _J , T _{TSG}		-55 to + 150	°C
Maximum Junction-to-Ambient *3	R _{θ JA}		62.5	°C/W

*1 Repetitive rating; pulse width limited by max. junction temperature.

*2 N-Channel I_{SD} ≤ 2.0A, di/dt ≤ 100A/μ s, V_{DD} ≤ V_{(BR)DSS}, T_J ≤ 150°C

P-Channel I_{SD} ≤ -1.3A, di/dt ≤ 84A/μ s, V_{DD} ≤ V_{(BR)DSS}, T_J ≤ 150°C

*3 Surface mounted on FR-4 board, t ≤ 10sec.

KRF9952■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Testconditons			Min	Typ	Max	Unit	
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250 \mu A$	N-Ch	30				V	
		$V_{GS} = 0V, I_D = -250 \mu A$		-30					
Breakdown Voltage Temp. Coefficient	$\Delta V_{(\text{BR})\text{DSS}} / \Delta T_J$	$I_D = 1\text{mA}, \text{Reference to } 25^\circ\text{C}$	N-Ch		0.015			V/°C	
		$I_D = -1\text{mA}, \text{Reference to } 25^\circ\text{C}$			0.015				
Static Drain-to-Source On-Resistance	$R_{DS(\text{on})}$	$V_{GS} = 10V, I_D = 2.2A^*1$	N-Ch		0.08	0.10		Ω	
		$V_{GS} = 4.5V, I_D = 1.0A^*1$			0.12	0.15			
Static Drain-to-Source On-Resistance	$R_{DS(\text{on})}$	$V_{GS} = -10V, I_D = -1.0A^*1$	P-Ch		0.165	0.250			
		$V_{GS} = -4.5V, I_D = -0.5A^*1$			0.290	0.400			
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu A$	N-Ch	1.0				V	
		$V_{DS} = V_{GS}, I_D = -250 \mu A$		-1.0					
Forward Transconductance	g_{fs}	$V_{DS} = 15V, I_D = 3.5A^*1$	N-Ch		12			S	
		$V_{DS} = -15V, I_D = -2.3A^*1$			2.4				
Drain-to-Source Leakage Current	I_{DSS}	$V_{DS} = 24V, V_{GS} = 0V$	N-Ch			2.0		μA	
		$V_{DS} = -24V, V_{GS} = 0V$				-2.0			
		$V_{DS} = 24V, V_{GS} = 0V, T_J = 125^\circ\text{C}$	N-Ch			25			
		$V_{DS} = -24V, V_{GS} = 0V, T_J = 125^\circ\text{C}$				-25			
Gate-to-Source Forward Leakage	I_{GSS}	$V_{GS} = \pm 20V$	N-Ch				±100	nA	
Total Gate Charge	Q_g	N-Channel $I_D = 1.8A, V_{DS} = 10V, V_{GS} = 10V$			N-Ch	6.9	14	nC	
					P-Ch	6.1	12		
Gate-to-Source Charge	Q_{gs}	P-Channel $I_D = -2.3A, V_{DS} = -10V, V_{GS} = -10V$	N-Ch		1.0	2.0			
			P-Ch		1.7	3.4			
Gate-to-Drain ("Miller") Charge	Q_{gd}		N-Ch		1.8	3.5			
			P-Ch		1.1	2.2			
Turn-On Delay Time	$t_{d(on)}$	N-Channel $V_{DD} = 10V, I_D = 1.0A, R_G = 6.0 \Omega$ P-Channel $R_D = 10 \Omega$			N-Ch	6.2	12	ns	
					P-Ch	9.7	19		
Rise Time	t_r				N-Ch	8.8	18		
					P-Ch	14	28		
Turn-Off Delay Time	$t_{d(off)}$				N-Ch	13	26		
					P-Ch	20	40		
Fall Time	t_f	N-Channel $V_{GS} = 0V, V_{DS} = 15V, f = 1.0\text{MHz}$ P-Channel $V_{GS} = 0V, V_{DS} = -15V, f = 1.0\text{MHz}$	N-Ch		3.0	6.0	pF		
					P-Ch	6.9	14		
Input Capacitance	C_{iss}		N-Ch		190				
					P-Ch	190			
Output Capacitance	C_{oss}		N-Ch		120				
					P-Ch	110			
Reverse Transfer Capacitance	C_{rss}		N-Ch		61		A		
					P-Ch	54			
Continuous Source Current (Body Diode)	I_s		N-Ch			1.7	A		
						-1.3			
Pulsed Source Current (Body Diode) *2	I_{SM}		N-Ch			16			
						16			

KRF9952

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons		Min	Typ	Max	Unit
Diode Forward Voltage	V _{SD}	T _J = 25°C, I _S = 1.25A, V _{GS} = 0V*3	N-Ch P-Ch		0.82	1.2	V
		T _J = 25°C, I _S = -1.25A, V _{GS} = 0V*3			-0.82	-1.2	
Reverse Recovery Time	t _{rr}	N-Channel	N-Ch P-Ch		27	53	ns
		T _J = 25°C, I _F = 1.25A, di/dt = 100A/ μ s*1			27	54	
Reverse RecoveryCharge	Q _{rr}	P-Channel	N-Ch P-Ch		28	57	nC
		T _J =25°C, I _F =-1.25A,di/dt=-100A/ μ s*1			31	62	

*1 Pulse width ≤ 300 μ s; duty cycle ≤ 2%.

*2 Repetitive rating; pulse width limited by max. junction temperature.

*3 N-Channel Starting T_J = 25°C, L = 22mH R_G = 25 Ω , I_{AS} = 2.0A.

P-Channel Starting T_J = 25°C, L = 67mH R_G = 25 Ω , I_{AS} = -1.3A.